

# GSDST14N1F

## Schottky Diode

### Product Description

Schottky Barrier Diode 40V and 1A



### Features

- Low Forward Voltage
- Trench Schottky Barrier Technology

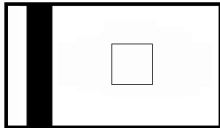
### Mechanical Data

- DFN1006-2L Package
- Color Band denotes Cathode End
- RoHS Compliant and Halogen Free

### Packages & Pin Assignments

DFN1006-2L		Equivalent Circuit
 TOP VIEW		
Pin	Description	
1	Anode	
2	Cathode	

### Ordering and Marking Information

Ordering Information			
Part Number	Package	Part Marking	Quantity / Reel
GSDST14N1F	DFN1006-2L	X	10,000 PCS
<div>- <b>Product Code:</b> GSDST14</div> <div>- <b>Package Code:</b> N1 is DFN1006-2L</div> <div>- <b>Green Level:</b> F is RoHS Compliant and Halogen Free</div>			
Marking Information			
		<div>- <b>Product Code:</b> □ Is X</div> <div>- <b>Color Band</b> Cathode End</div>	

GSDST14N1F

## Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise specified)

Symbol	Parameter	Rating	Unit
V <sub>RRM</sub>	Maximum repetitive peak reverse voltage	40	V
V <sub>RMS</sub>	Maximum RMS voltage	28	V
V <sub>DC</sub>	Maximum DC blocking voltage	40	V
I <sub>F(AV)</sub>	Maximum average forward rectified current	1	A
I <sub>FSM</sub>	Peak forward surge current*	5	A
P <sub>D</sub>	Power Dissipation T <sub>A</sub> =25°C	0.6	W
T <sub>J</sub>	Junction Temperature Range	-55 to +150	°C
T <sub>STG</sub>	Storage Temperature Range	-55 to +150	°C

\* 8.3 ms single half sine-wave superimposed on rated load.

## Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise specified)

Symbol	Description	Conditions	Min	Max	Unit
V <sub>BR</sub>	Breakdown Voltage	I <sub>R</sub> =0.5mA	40	-	V
V <sub>F</sub>	Instantaneous Forward Voltage	I <sub>F</sub> =100mA	-	375	mV
		I <sub>F</sub> =500mA	-	485	
		I <sub>F</sub> =1000mA	-	600	
			-		
I <sub>R</sub>	Reverse Leakage Current	V <sub>R</sub> = 10V	-	30	μA
		V <sub>R</sub> = 40V	-	100	

## Performance Characteristics (T<sub>A</sub>=25°C unless otherwise specified)

Fig.1 - Forward Current Derating Curve

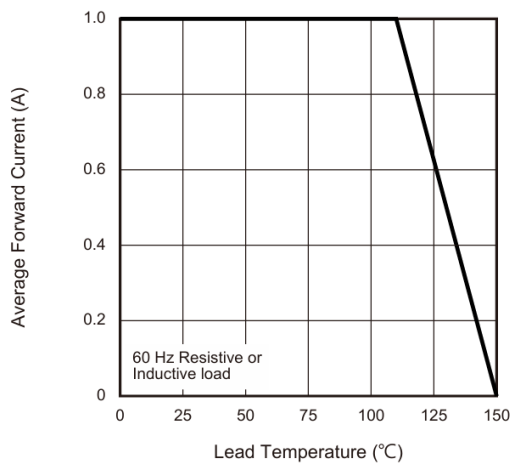


Fig.2 - Typical Instantaneous Forward Characteristics

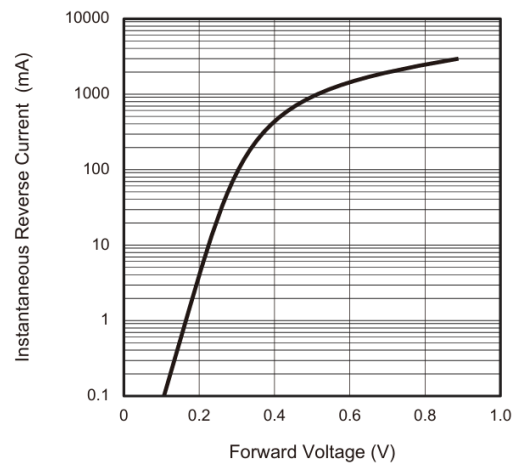


Fig.3 - Typical Reverse Characteristics

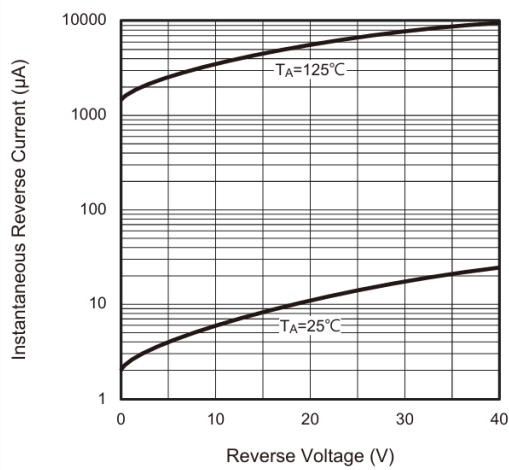
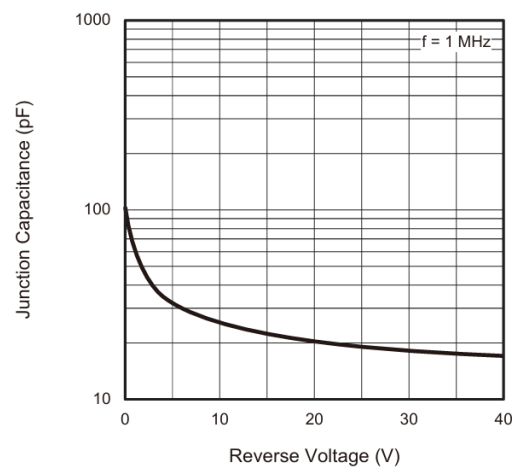
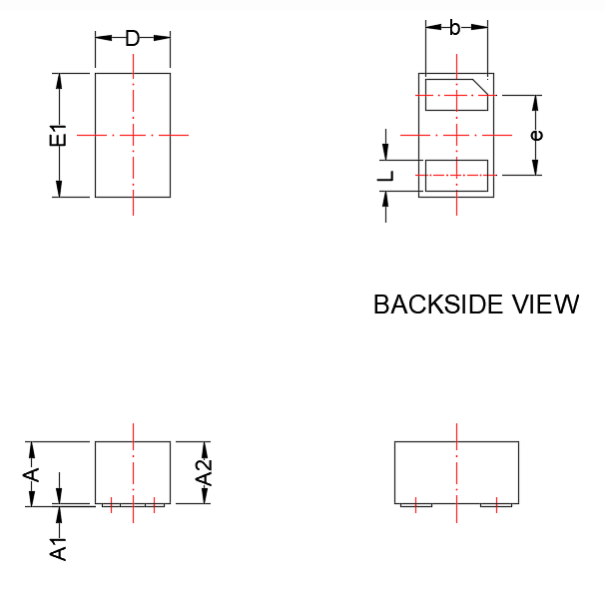


Fig.4 - Capacitance Characteristics

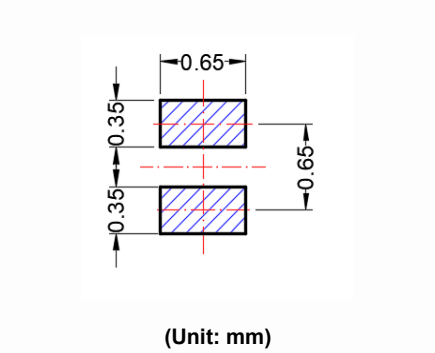


# DFN1006-2L

## Package Dimension



## Recommended Land Pattern







Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.45	0.60	0.018	0.024
A1	0.00	0.05	0.000	0.002
A2	0.40	0.60	0.016	0.024
b	0.45	0.55	0.018	0.022
D	0.55	0.65	0.022	0.026
E1	0.95	1.05	0.037	0.041
e1	0.65 BSC		0.026 BSC	
L	0.20	0.30	0.008	0.012



NOTE:  
DIMENSION D DOES NOT INCLUDE MOLD FLASH,PROTRUSIONS OR GATE BURRS.

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